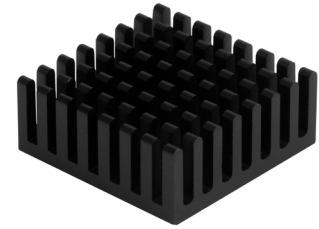


MODEL: HSB24-252510 | DESCRIPTION: HEAT SINK

FEATURES

- BGA design
- small footprint
- top mount
- aluminum alloy



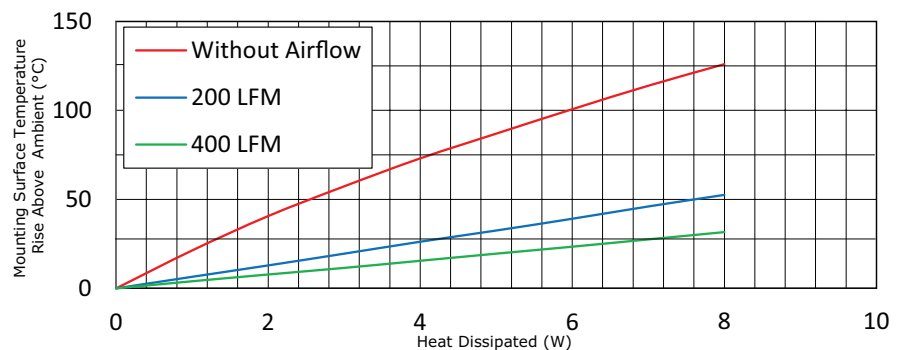
MODEL

MODEL	thermal resistance ¹				power dissipation ¹ @ 75°C ΔT, nat conv (W)
	@ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	
HSB24-252510	18.10	21.3	6.5	4.0	4.14

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) (°C)		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	21.3	6.5	4.0
2	40.6	12.9	7.8
3	57.3	19.5	11.5
4	73.0	26.2	15.5
5	86.9	32.5	19.5
6	100.6	39.1	23.4
7	113.8	46.0	27.5
8	125.9	52.5	31.6

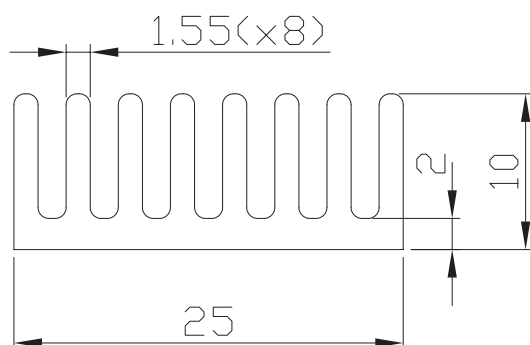
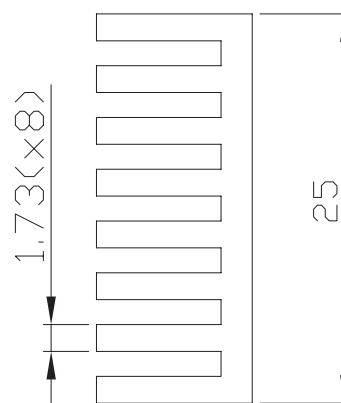
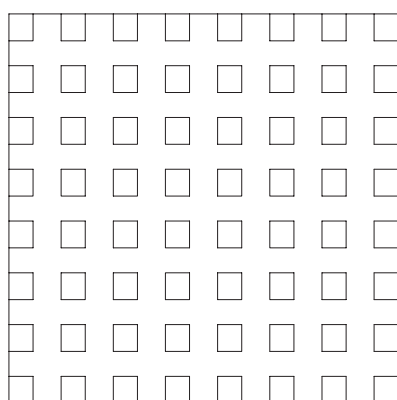


T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature

MECHANICAL DRAWING

units: mm
tolerance: ± 0.5 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	8.8 g



REVISION HISTORY

rev.	description	date
1.0	initial release	04/22/2022

The revision history provided is for informational purposes only and is believed to be accurate.

CUI DEVICES

CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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